

Electronic Patent Application Fee Transmittal

Application Number:	10770890			
Filing Date:	02-Feb-2004			
Title of Invention:	METHODS FOR FORMING ASSEMBLIES AND PACKAGES THAT INCLUDE STACKED SEMICONDUCTOR DEVICES SEPARATED A DISTANCE DEFINED BY ADHESIVE MATERIAL INTERPOSED THEREBETWEEN			
First Named Inventor/Applicant Name:	James M. Derderian			
Filer:	Brick Glenn Power/Nancy Johnson			
Attorney Docket Number:	2269-4817.3US (01-0103.03			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1440	1440
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				1740